TOSHIBA High Efficiency Rectifier (HED) Silicon Epitaxial Junction Type

1R5DL41A

Switching Mode Power Supply Applications

- Repetitive Peak Reverse Voltage: VRRM = 200 V
- Average Forward Current: IF (AV) = 1.5 A (Ta = 25°C)
- Very Fast Reverse-Recovery Time: $t_{rr} = 35 \text{ ns (max)}$
- Low Forward Voltage: V_{FM} = 0.98 V (max)
- Available to Reduce Switching Losses and Output Noise

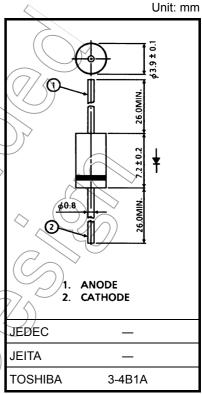
Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	200	(\sqrt{y})
Average forward current (Ta = 25°C)	I _{F (AV)}	1.5	A
Peak one cycle surge forward current (non-repetitive)	I _{FSM}	60 (50 Hz)	^
		66 (60 (Hz)	
Junction temperature	Tj	-40 to 150	°C
Storage temperature	T _{stg}	40 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the

Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

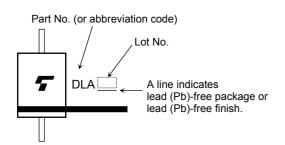


Weight: 0.47 g (typ.)

Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Peak forward voltage	V _{FM}	I _{FM} = 1.5 A		_	0.98	V
Repetitive peak reverse current	IRRM	V _{RRM} = 200 V		_	100	μΑ
Reverse recovery time	(t _{rr}	$I_F = 1 \text{ A, di/dt} = -30 \text{ A/}\mu\text{s}$		_	35	ns
Forward recovery time	t _{fr}	I _F = 1.0 A		_	100	ns
Thermal resistance	R _{th (j-a)}	Junction to Ambient		_	100	°C/W
Thermal resistance	Rth (j-ℓ)	Junction to Lead	_	_	30	°C/W

Marking



Abbreviation Code	Part No.		
DLA	1R5DL41A		

Handling Precaution

The absolute maximum ratings denote the absolute maximum ratings, which are rated values and must not be exceeded during operation, even for an instant. The following are the general derating methods that we recommend when you design a circuit with a device.

VRRM: We recommend that the worst case voltage, including surge voltage, be no greater than 80% of the absolute maximum rating of VRRM for a DC circuit and be no greater than 50% of that of VRRM for an AC circuit. VRRM has a temperature coefficient of 0.1%/°C. Take this temperature coefficient into account designing a device at low temperature.

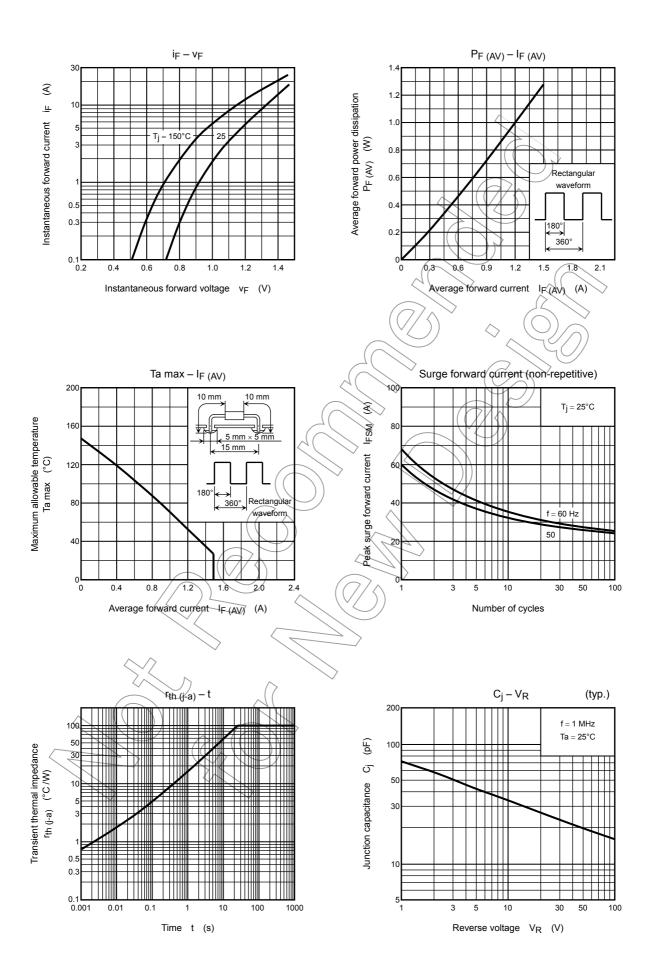
IF(AV): We recommend that the worst case current be no greater than 80% of the absolute maximum rating of IF(AV). Carry out adequate heat design. If you can't design a circuit with excellent heat radiation, set the margin by using an allowable Tamax-IF(AV) curve.

This rating specifies the non-repetitive peak current in one cycle of a 50-Hz sine wave, condition angle 180. Therefore, this is only applied for an abnormal operation, which seldom occurs during the lifespan of the device.

We recommend that a device be used at a Tj of below 120°C under the worst load and heat radiation conditions.

Thermal resistance between junction and ambient fluctuates depending on the device's mounting condition. When using a device, design a circuit board and a soldering land size to match the appropriate thermal resistance value.





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 In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc.
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